#### TOSHIBA PHOTOCOUPLER GaAlAs IRED & PHOTO-DIODE ARRAY

# **TLP3924**

# TELECOMMUNICATION PROGRAMMABLE CONTROLLERS MOS FET GATE DRIVER

The TOSHIBA SSOP coupler TLP3924 is a small outline coupler, suitable for surface mount assembly.

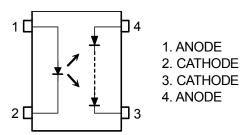
The TLP3924 consists of a GaAlAs light emitting diode, optically coupled to a series connected photo diode array which is suitable for MOSFET gate drive.

#### **Features**

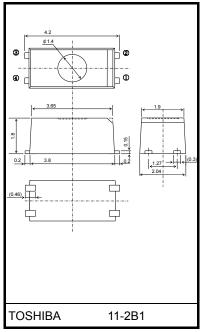
• 4 pin SSOP (SSOP4) : 1.8 mm high, 1.27 mm pitch

Open Voltage : 30V (min)
 Short Current : 4µA (min)
 Isolation Voltage : 1500Vrms (min)

#### Pin Configuration (top view)



Unit in mm



Weight: 0.03 g

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
	Forward Current	lF	30	mA
LED	Forward Current Derating (Ta ≥ 25°C)	Δl <sub>F</sub> / °C	-0.3	mA / °C
	Reverse Voltage	V <sub>R</sub>	5	V
	Junction Temperature	Tj	125	°C
DETECTOR	Forward Current	I <sub>FD</sub>	50	μA
	Reverse Voltage	V <sub>RD</sub>	10	٧
	Junction Temperature	Tj	125	°C
Storage Temperature Range		T <sub>stg</sub>	-55~125	°C
Operating Temperature Range		T <sub>opr</sub>	-40~85	°C
Lead Soldering Temperature (10 s)		T <sub>sol</sub>	260	°C
Isolation Voltage (AC, 1 min., R.H. ≤ 60%) (Note 1)		BVS	1500	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(Note 1): Device considered a two terminal device: Pins 1 and 2 shorted together and pins 3 and 4 shorted together.

#### Caution

This device is sensitive to electrostatic discharge. When using this device, please ensure that all tools and equipment are earthed.

#### **Recommended Operating Conditions (Note 2)**

Characteristic	Symbol	Min	Тур.	Max	Unit
Forward Current	lF	7	_	20	mA
Operating Temperature	T <sub>opr</sub>	-25	_	65	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

#### Individual Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
	Forward Voltage	$V_{F}$	I <sub>F</sub> = 10 mA	1.15	1.30	1.45	V
LED	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V	_	_	10	μΑ
	Capacitance	C <sub>T</sub>	V = 0, f = 1 MHz	_	30	_	pF
	Forward Voltage	$V_{FD}$	I <sub>FD</sub> = 10 μA	_	39	_	V
DETECTOR	Reverse Current	I <sub>RD</sub>	V <sub>RD</sub> = 10 V	_	1	_	nA
	Capacitance (Anode to Cathode)	C <sub>TD</sub>	V = 0, f = 1 MHz	_	1.5	_	pF

# **Coupled Electrical Characteristics (Ta = 25°C)**

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Open-Circuit Voltage	V <sub>OC</sub>	I <sub>F</sub> = 10 mA	30	_	_	V
Short-Circuit Current	Isc	I <sub>F</sub> = 10 mA	4	_		μA

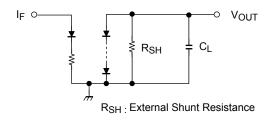
### **Isolation Characteristics (Ta = 25°C)**

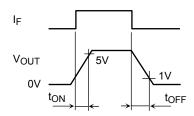
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Capacitance Input to Output	CS	V <sub>S</sub> = 0, f = 1 MHz	_	0.8	_	pF
Isolation Resistance	R <sub>S</sub>	V <sub>S</sub> = 500 V, R.H. ≤ 60%	5×10 <sup>10</sup>	10 <sup>14</sup>	_	Ω
Isolation Voltage	BVS	AC, 1 minute	1500	_	_	- Vrms
		AC, 1 second in oil	_	3000	_	
		DC, 1 minute in oil	_	3000	_	Vdc

## **Switching Characteristics (Ta = 25°C)**

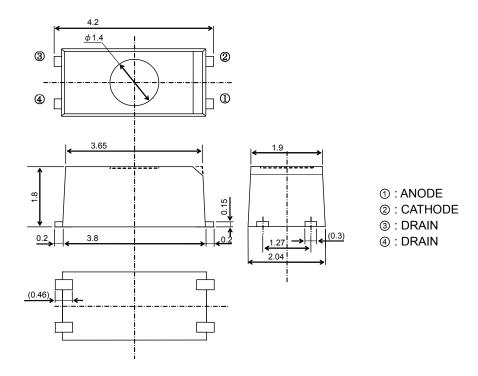
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Turn-on Time	t <sub>ON</sub>	$I_F$ = 10 mA, $R_{SH}$ = 510 kΩ	_	_	_	ms
Turn-off Time	toff	$C_L = 1000pF$ (Note 3)	_	_	_	ms

(Note 3): SWITCHING TIME TEST CIRCUIT





#### **OUTLINE DRAWING**



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